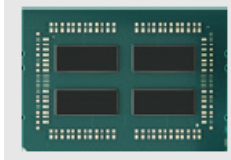
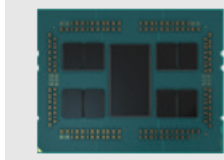
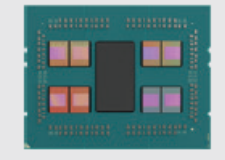
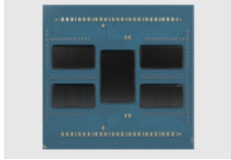


Table 1 : The Multi-die Architecture has enabled significant improvements for each processor generation since the beginning

| | AMD EPYC 7001 'NAPLES' | AMD EPYC 7002 'ROME' | AMD EPYC 7003 'MILAN' | AMD EPYC 9004 'GENOA' |
|--|---|--|---|---|
| |  |  |  |  |
| Core Architecture | 'Zen' | 'Zen 2' | 'Zen 3' | 'Zen 4' |
| Cores | 8 to 32 | 8 to 64 | 8 to 64 | 16 to 96 |
| IPC Improvement Over Prior Generation | N/A | 24% (ROM-236) | 19%(MLN-003) | 14%(EPYC-038) |
| Max L3 ache | Up to 64MB | Up to 256MB | Up to 256MB (Note*) | Up to 384MB |
| PCIe Lanes | Up to 128 Gen3 | Up to 128 Gen3 | Up to 128 Gen4 | Up to 128 Gen5 8 bonus lanes Gen3 |
| CPU Process Technology | 14nm | 7nm | 7nm | 5nm |
| I/O die Process Technology | N/A | 14nm | 14nm | 6nm |
| Power(Configurable TDP[cTDP]) | 120W-200W | 120W-280W | 155W-280W | 200W-400W |
| Max Memory Capacity | 2TB DDR3-2400/2666 | 4TB DDR4-3200 | 4TB DDR4-3200 | 6TB DDR5-4800 |

(Note*) : Up to 768MB for processors with AMD 3D V-Cache™ technology.

ROM-236: Based on AMD internal testing, average per thread performance improvement at ISO-frequency on a 32-core, 64-thread, 2nd generation AMD EPYC™ platform as compared to 32-core 64-thread 1st generation AMD EPYC™ platform measured on a selected

set of workloads including sub-components of SPEC CPU® 2017_int and representative server workloads.

MLN-003: Based on AMD internal testing as of 02/1/2021, average performance improvement at ISO-frequency on an AMD EPYC™ 72F3 (8C/8T, 3.7GHz) compared to an AMD EPYC™ 7F32 (8C/8T, 3.7GHz), per-core, single thread, using a select set of workloads including SPECrate®2017_int_base, SPECrate®2017_fp_base, and representative server workloads.

EPYC-038: Based on AMD internal testing as of 09/19/2022, geometric performance improvement at the same fixed-frequency on a 4th Gen AMD EPYC™ 9554 CPU compared to a 3rd Gen AMD EPYC™ 7763 CPU using a select set of workloads (33) including est. SPECrate®2017_int_base, est. SPECrate®2017_fp_base, and representative server workloads.

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